IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Distri				Type * Declaration Class * ute Class 6 - RoHS Yes/No, Homogeneous Mater				ous Materia	als and Mfg	Informati	ion		
Supplier	· Information														
Company	name*		Company un	ique ID		Ţ	Unique ID Au	hority				Response 1	Date*		
onsemi												2024-05-08	3		
Contact N	ame		Title - Conta	Title - Contact			Phone - Contact*					Email - Contact*			
Product-E	Env-Stewards	Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				
Authorize	d Representative*	Title - Repre	Title - Representative			Phone - Representative*					Email - Representative*				
Product-E	Env-Stewards		Product Envi	ro Compliance			NA					Product-H	nv-Stew	ards@onsemi.co	om
	Requester Item Number	Mfr Iter	n Number	Mfr Item Name			Effective Dat	e Version	1	Manufacturii	ng Site	We	ight*	UOM	Unit Type
		MT9P0	06I12STCU-	5 MP 1/2.5 CIS			2024-05-08		1	ЛҮ5		258	3.99	mg	Each
Manufa	cturing Proccess Informa	ntion													
	Terminal Plating / Grid Array M	ninal Plating / Grid Array Material		Γerminal Base Alloy J-		MSL Rating Pea		eak Process Body Temperature Ma		e Max Tin	Time at Peak Temperatu		Numb	er of Reflow Cyo	eles
	Precious metal (e.g. Ag,Au, Ni Sn)	PdAu) (no	CU Alloy		4		260		С	30		seconds	3		
Comments			·												
or more i	information regarding materia	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	led
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybrominated Biphenyls (Pl	aterial for Cadmium and quantity limit of 0.1% by BB), Polybrominated Diphenyl Ethers (PBDE), an		
cadmium, hexavalentchromium, polybromir contains a RoHS restricted substance inexce encompass all such components. Supplier ce as of the date that Supplier completes this fo Company acknowledges that Supplier may l independently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated dipless of an applicable quantity limit, please intifies that it gathered the information it prome. Supplier acknowledges that Company have relied on information provided by other by others, Supplier agrees that, at a mining and the Supplier enter into a written agree esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substational substance below which, if any, RoHS exemption by desired in this form using appropriate method will rely on this certification in determining ters in completing this form, and that Supplies have provided certification between the will respect to the identified part, the Company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects the company is the co	ws of the European Union member states) of the pnce") in excess of the applicable quantity limit iden you believe may apply. If the part is an assemble is to ensure its accuracy and that such information the compliance of its products with European Union may not have independently verified such informs regarding their contributions to the part, and tho terms and conditions of that agreement, including the provides in this formation information the Supplier provides in this formation.	entified above. If a y with lower level is true and correct on member state la nation. However, in se certifications are any warranty rigl	n homogeneous material within the part components, the declaration shall t to the best of its knowledge and belief, aws that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the hts and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per	the definition above except for defined Ro	oHS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	59.5	mg		Misc.	proprietary data		0.2261	mg
			Supplier	Silicon (Si)	7440-21-3		58.6848	mg
			Supplier	Aluminum (Al)	7429-90-5		0.589	mg
Die Attach	2.2	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.825	mg
			Supplier	Ethylene Glycol	107-21-1		0.022	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.066	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.462	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.825	mg
Imaging Lens	55.32	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.766	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.766	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.766	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.766	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2766	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.766	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.766	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		38.4474	mg
Lid Attach	2.4	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.7584	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1248	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.7584	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.7584	mg
Mold Compound-Black	55.01	mg		Phenolic Resin	proprietary data		8.2515	mg
			Supplier	Oxirane	39817-09-9		8.2515	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.6503	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5501	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.2064	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1002	mg
Substrate and Solder Mask	84.3	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		17.5934	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.0875	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2698	mg
			Supplier	Acetophenone Derivative	Proprietary Data		1.627	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2698	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2698	mg
			В	Nickel (Ni)	7440-02-0	1.0285	mg
			Supplier	Gold (Au)	7440-57-5	0.2192	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.2793	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	10.8578	mg
			Supplier	Copper (Cu)	7440-50-8	39.385	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.4131	mg
Wire Bond - Au	0.26	mg	Supplier	Gold (Au)	7440-57-5	0.26	mg